

SOT1435-1

plastic, thermal enhanced super thin quad flat package; no leads; 16 terminals; body 2.0 x 2.0 x 0.3 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2QFN
Package type industry code	HX2QFN16
Package style descriptive code	HQFP (thermal enhanced quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-3-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.95	-	2	2.05	mm
E	package width	1.95	-	2	2.05	mm
A	seated height	0.28	-	0.3	0.33	mm
e	nominal pitch	-	-	0.35	-	mm
n ₂	actual quantity of termination	-	-	16	-	

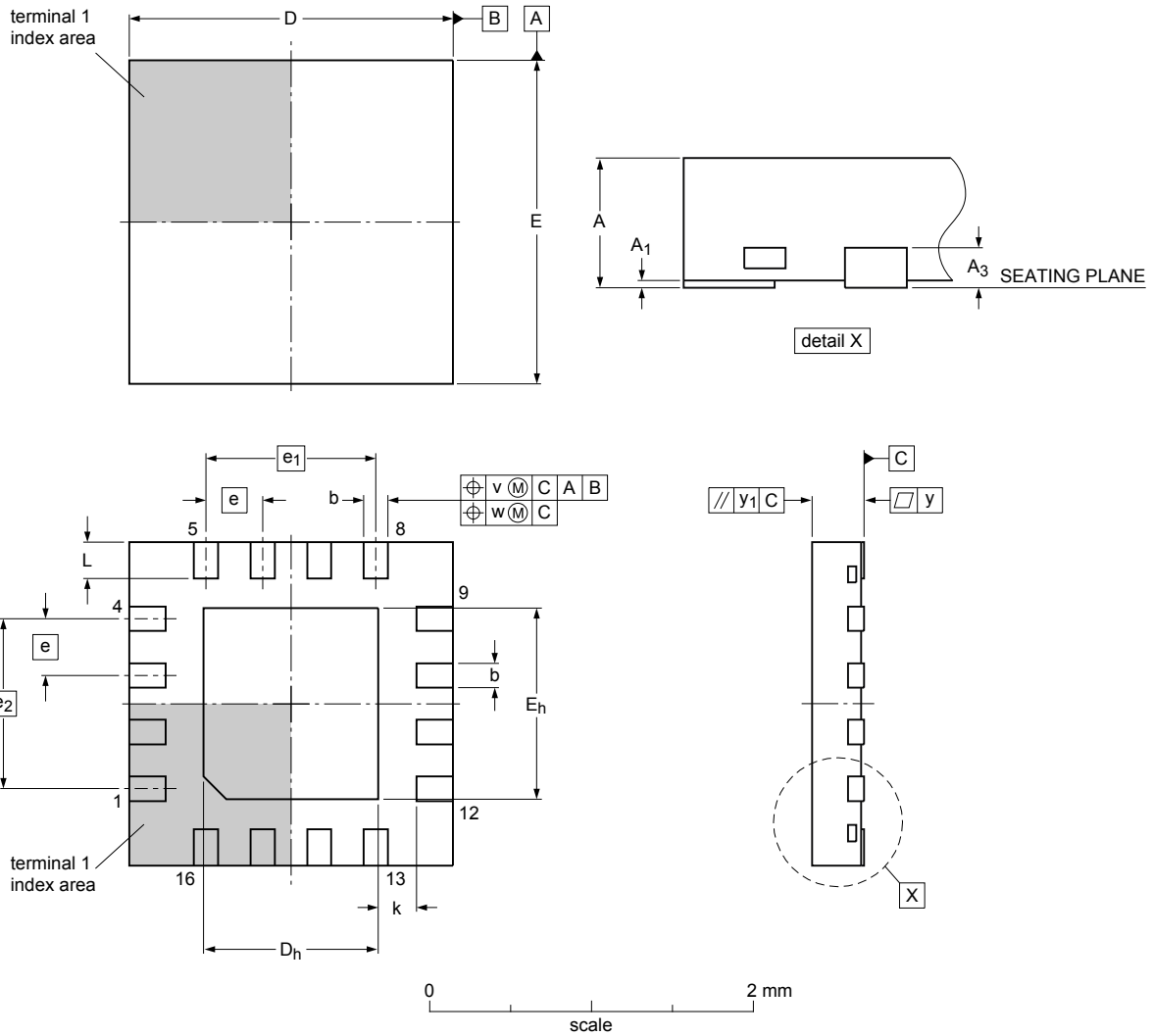


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2. Package outline

HX2QFN16: plastic, thermal enhanced super thin quad flat package; no leads; 16 terminals; body 2.0 x 2.0 x 0.3 mm

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Dimensions (mm are the original dimensions)

Unit	A ⁽¹⁾	A ₁	A ₃	b	D	D _h	E	E _h	e	e ₁	e ₂	k	L	v	w	y	y ₁
max	0.33	0.05		0.20	2.05	1.13	2.05	1.23					0.275				
nom	0.30	0.02	0.10	0.15	2.00	1.08	2.00	1.18	0.35	1.05	1.05		0.225	0.07	0.05	0.08	0.1
min	0.28	0.00		0.10	1.95	1.03	1.95	1.13				0.185	0.175				

Note

1. Plastic or metal protrusions of 0.05 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1435-1					15-02-12- 15-03-05

Fig. 1. Package outline HX2QFN16 (SOT1435-1)

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3. Legal information

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Date of release: 8 February 2016
